



Final Product Change Notification

201312024F01

Issue Date: 23-Dec-2013
Effective Date: 23-Mar-2014

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to [view this notification online](#)



QUALITY

Change Category

- | | | | |
|---|--|---|--|
| <input checked="" type="checkbox"/> Wafer Fab process | <input checked="" type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input checked="" type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

SOT223 Copper Wire - Automotive

Details of this Change

NXP will introduce variants of SOT223 PowerMOS devices which will use copper wirebonds rather than gold. This will ensure a commercially sustainable platform for the continued manufacture of these devices. The product performance will be unchanged.

Why do we Implement this Change

Copper wire has less electrical resistance than Gold, is more resilient and performs better in high current analogue devices such as Power MOSFETS

Identification of Affected Products

Replacement part type created, see Parts Affected list

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 01-Apr-2014

Impact

no impact to the product's functionality anticipated.
No change to the product's functionality.
There is no change to the form, fit or function of the product.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

N/A - Replacement part type created

Related Notifications

Notification Issue Date Effective Date Title

2013060171 02-Jul-2013 06-Jul-2013 Change of resin hardener of two Henkel mold compounds used in NXP products

Additional information

Affected products and sales history information
Self qualification _____

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 22-Jan-2014.

Remarks

This product change notification is for your company internal use and for your use as Distributor towards your direct customers. You are responsible for the correct circulation of this information to your direct customers. NXP does not accept liability for any failure to notify your direct customers of this change within the appropriate timeframe, or for any other incorrect further distribution of this information.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

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